

NSP1632 Series

MEMS Absolute Pressure Sensor Die

Datasheet (EN) 1.0

Product Overview

Novosense NSP1632 series MEMS pressure sensors are high-performance and high-reliability MEMS absolute pressure sensor dies, based on the principle of monocrystalline silicon high sensitivity piezoresistive effect, and manufactured by the advanced MEMS technology. The NSP1632 series MEMS absolute pressure sensors are qualified according to AEC-Q103 and guaranteed the accuracy and stability better than 1% FS in overall lifetime, the typical pressure ranges are 0~100kPa and 0~200kPa, widely used in automotive electronics, consumer electronics, industrial controls, etc. The corrosion-resistant Pt metal bond pads make it to be suitable for harsh environment applications such as Turbo-MAP, EGR-MAP, BPS etc. especially.

The wafer manufactured platform of NSP1632 series MEMS absolute pressure sensors is verified to fulfill the International Automotive Standard IATF16949:2016. Each wafer is inspected both in the process and at the end of process by 100% AOI and the electronic AOI wafer map is provided for each wafer. For additional shipping options, please contact Novosense sales.

Key Features

- Pressure range: 0~100kPa, 200kPa
- Operating temperature: -40~150°C
- Die size: 1.0mmx1.0mmx0.4mm
- Accuracy and Stability better than 1%FS

- Optional corrosion-resistant Pt metal bond pad
- IATF16949 certificated manufactured platform
- AEC-Q103 automotive standards qualified
- ROHS & REACH compliant

Applications

- Intake Manifold Pressure Sensor
- Vacuum Booster Pressure Sensor
- Electric Vehicle Battery Pack Pressure Sensor
- Barometric Pressure Sensors
- Industrial Controls

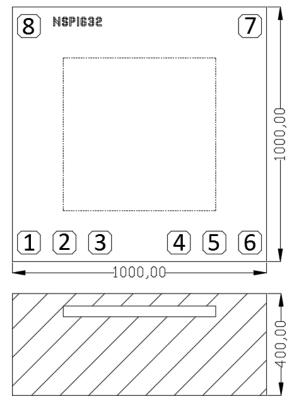
Device Information

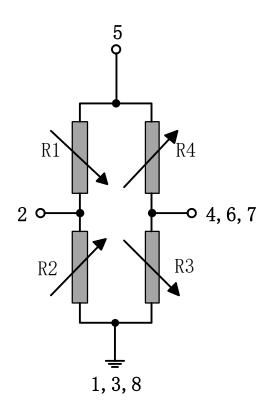
Part Number	Span	Bond Pad Metal
NSP1632-Bxx100	0~100kPa	Pt Metal
NSP1632-Bxx200	0~200kPa	Pt Metal

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1. Dimensions And Diagram





Pad opening: 90x90um

NO.	Pad description	Symbol	Value	Coordinate X-Axis (μm)	Coordinate Y-Axis (μm)
1	Negative Supply Voltage	GND	0V	65	75
2	Positive Sensor Output	Vout+	-	205	75
3	Negative Sensor Output	GND	0V	345	75
4	Negative Sensor Output	Vout-	-	655	75
5	Positive Supply Voltage	VDD	+5V	795	75
6	Negative Sensor Output	Vout-	-	935	75
7	Negative Sensor Output	Vout-	-	935	925
8	Negative Supply Voltage	GND	0V	65	925

Notes:

- 1. All dimensions are in micron.
- 2. Bond pad opening size: 90x90um.
- 3. Bond pad metal: Pt, Thickness: 200nm.

2. Absolute Maximum Ratings

NO.	Parameters	Symbol	Min	Тур	Max	Unit
1	Supply voltage	VDD			12	V
2	Operating temperature ¹	T _{OP}	-40		150	$^{\circ}\mathbb{C}$
3	Storage temperature	T _{STG}	-40		150	$^{\circ}\mathbb{C}$
4	Proof pressure	P _{proof}	3x			FS
5	Burst pressure	P _{Burst}	5x			FS

3. Characteristic

Measured at 5V supply and 25 °C, unless otherwise specified.

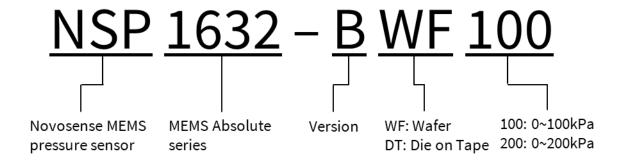
NO.	Parameters		Symbol	Min ³	Typ¹′²	Max ³	Unit
1	Pressure range		Span	0	100,200,500	1000	kPa
2	Full spap output	100kPa	Varit	50	80	110	mV
2	Full span output	200kPa	Vout	55	85	115	
3	Offset Voltage ³		Offset	-30	±10	30	mV
4	Temperature coefficient of span⁴		TCS	-0.25	-0.20	-0.15	%FS/
5	Temperature coefficient of offset⁴		TCO	-80	±10	80	μV/°C
6	Temperature coefficient of bridge resistance ⁴		TCR	0.04	0.08	0.12	%FS/
7	Non-linearity⁵		NL_{TS}	-0.3	±0.1	0.3	%FS
8	Bridge resistance		R _B	4.3	5.3	6.3	kΩ
9	Pressure hysteresis ⁶		P _{HYS}	-0.1	±0.05	0.1	%FS
10	Temperature hysteresis ⁵		T _{HYS}	-0.2	±0.1	0.2	%FS

Notes:

- 1. Measured on a sample basis and based on special MEMS only package. The sensor performance may change depending on the die attach material and the assemble process.
- 2. Measured at 0~100kPa pressure range and for the other pressure ranges, please contact Novosense sales.
- 3. Output voltage at zero pressure.
- 4. Measured from -40°C to 150°C.
- 5. Defined as the best fit straight line.
- 6. Dry non-corrosive and pollution-free gas.

4. Order Information

NO.	Order NO.	Span	Comment
1	NSP1632-BWF100	0~100kpa	Wafer
2	NSP1632-BDT100	0~100kpa	Die on Tape
3	NSP1632-BWF200	0~200kpa	Wafer
4	NSP1632-BDT200	0~200kpa	Die on Tape



5. Revision History

Revision	Description	Date
0.1	Initial Version.	2022/5/16
1.0	Formal Version	2022/6/6

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